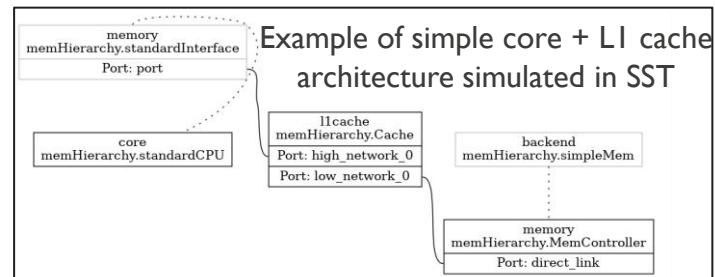


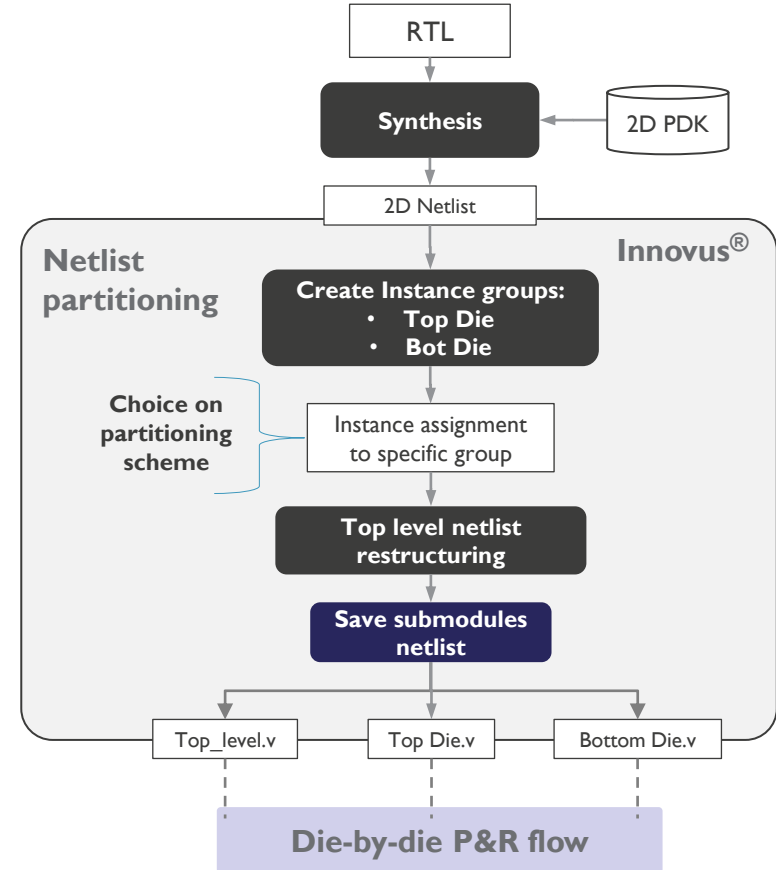
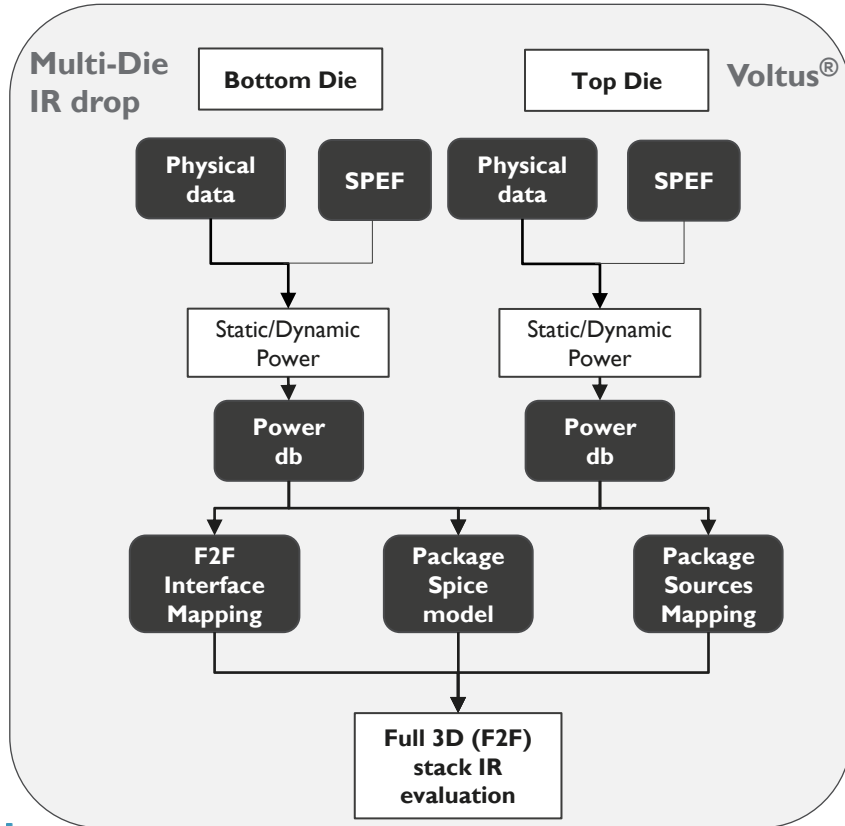
# Summary

- Worked on novel methodologies for 3D-IC block level design and signoff
  - Fine-Pitch 3D integration with Hybrid bonding on HPC SoC (April 2021 PTW – J107) and AI SoC (April 2022 PTW – D116)
- Evaluation of Backside PDN for High-Performance Computing
  - [Block-level Evaluation and Optimization of Backside PDN for High-Performance Computing at the AI4 node | IEEE Conference Publication | IEEE Xplore](#)
- PPA comparison at SoC level with different CMOS technologies and DTCO/STCO scaling boosters
  - [Nanosheet and Forksheet width modulation](#) (October 2021 PTW – Y112)
  - [Backside signal routing](#) (April 2021 PTW – Y106)
- Computer architecture and system modeling and exploration
  - [SST Simulator](#), Cadence Helium
- Several supervised PhD and Master student projects
  - Application-Aware SoC optimization
  - Chiptlets-based SoC cost model (VLSI 2024 submitted)
- RTL Logic design for a compute block (current project)



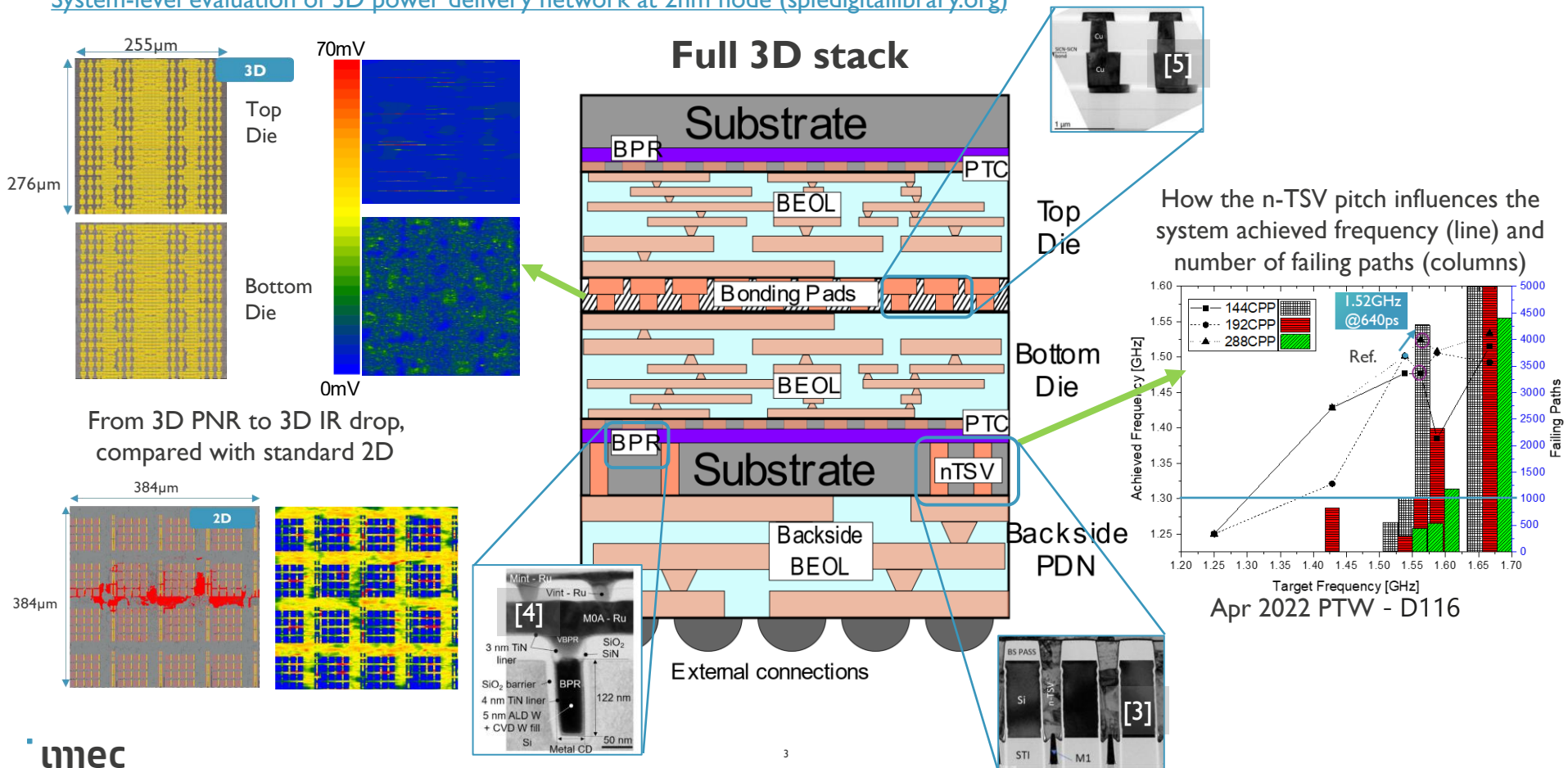
# Examples of developed design methodologies for 3D ICs

All built within commercial EDA tools



# Methodologies application on a memory-dominated SoC for AI

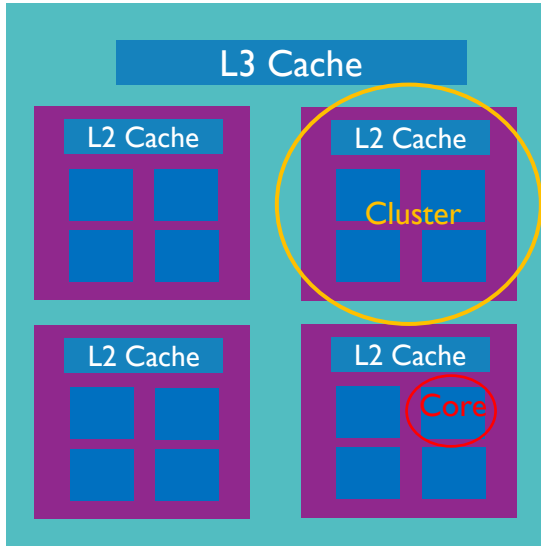
System-level evaluation of 3D power delivery network at 2nm node ([spiedigitallibrary.org](https://spiedigitallibrary.org))



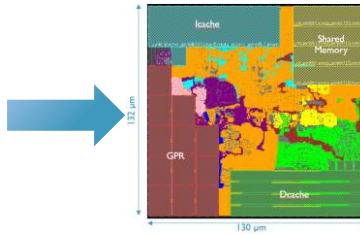
# Application-Aware SoC Optimization

Proposed project, ongoing with 2<sup>nd</sup> back-to-back student

Vortex Platform [OpenSource GP-GPU \(gatech.edu\)](https://open-source-gp-gpu.github.io)



- Basic configuration
- 1 cluster with 1 core
  - 4 warps and 4 Threads
  - 16KB L1 cache
  - No L2 or L3 caches



We have the PNR of a block with logic and memory, but does it make sense from the application point of view?

Co-Optimization options

- Optimize Fplan to reduce M2 utilization
- Adjust Icache capacity for area reduction
- ...

Now we have an Application-aware PD implementation!

Representative Matrix-Matrix multiplication workload and RTL simulation

